

# BREVET DE TECHNICIEN SUPERIEUR

## SYSTEMES ELECTRONIQUES

### SESSION 2008

#### Epreuve U4 : ELECTRONIQUE

##### DOSSIER TECHNIQUE

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<b>SESSION 2008</b>	<b>CODE :</b>
<b>BTS SYSTEMES ELECTRONIQUES</b>	
<b>Epreuve : ELECTRONIQUE</b>	
<b>Durée : 4 heures</b>	<b>Coefficient : 4</b>

Série E12 :  
1 – 1.2 – 1.5 – 1.8 – 2.2 – 2.7 – 3.3 – 3.9 – 4.7 – 5.6 – 6.8 – 8.2

ICL3232

Pinouts (Continued)	ICL3221, ICL3222, ICL3223, ICL3224, ICL3241, ICL3243		ICL3221, ICL3222, ICL3223, ICL3224, ICL3241, ICL3243	
	<div>ICL3232 (PDIP, SOIC, SSOP, TSSOP) TOP VIEW</div> <div><div><div>C1+</div><div>V+</div><div>C1-</div><div>C2+</div><div>C2-</div><div>T2OUT</div><div>R2IN</div></div><div><div>16</div><div>15</div><div>14</div><div>13</div><div>12</div><div>11</div><div>10</div><div>9</div></div><div><div>VCC</div><div>GND</div><div>T1OUT</div><div>R1IN</div><div>T1IN</div><div>T2IN</div><div>R2OUT</div></div></div>		<div>ICL3221, ICL3222, ICL3223, ICL3224, ICL3241, ICL3243</div>	
Pin Descriptions	<div>Pin</div> <div>Function</div>		<div>Pin</div> <div>Function</div>	
	<div>VCC</div> <div>System power supply input (3.0V to 5.5V).</div>		<div>VCC</div> <div>System power supply input (3.0V to 5.5V).</div>	
	<div>V+</div> <div>Internally generated positive transmitter supply (+5.5V).</div>		<div>V+</div> <div>Internally generated positive transmitter supply (+5.5V).</div>	
	<div>V-</div> <div>Internally generated negative transmitter supply (-5.5V).</div>		<div>V-</div> <div>Internally generated negative transmitter supply (-5.5V).</div>	
	<div>GND</div> <div>Ground connection.</div>		<div>GND</div> <div>Ground connection.</div>	
	<div>C1+</div> <div>External capacitor (voltage doubler) is connected to this lead.</div>		<div>C1+</div> <div>External capacitor (voltage doubler) is connected to this lead.</div>	
	<div>C1-</div> <div>External capacitor (voltage doubler) is connected to this lead.</div>		<div>C1-</div> <div>External capacitor (voltage doubler) is connected to this lead.</div>	
	<div>C2+</div> <div>External capacitor (voltage inverter) is connected to this lead.</div>		<div>C2+</div> <div>External capacitor (voltage inverter) is connected to this lead.</div>	
	<div>C2-</div> <div>External capacitor (voltage inverter) is connected to this lead.</div>		<div>C2-</div> <div>External capacitor (voltage inverter) is connected to this lead.</div>	
	<div>T1N</div> <div>TTL/CMOS compatible transmitter inputs.</div>		<div>T1N</div> <div>TTL/CMOS compatible transmitter inputs.</div>	
	<div>TOUT</div> <div>RS-232 level (nominally ±5.5V) transmitter outputs.</div>		<div>TOUT</div> <div>RS-232 level (nominally ±5.5V) transmitter outputs.</div>	
	<div>R1N</div> <div>RS-232 compatible receiver inputs.</div>		<div>R1N</div> <div>RS-232 compatible receiver inputs.</div>	
	<div>ROUT</div> <div>TTL/CMOS level receiver outputs.</div>		<div>ROUT</div> <div>TTL/CMOS level receiver outputs.</div>	
	<div>ROUTB</div> <div>TTL/CMOS level, noninverting, always enabled receiver outputs.</div>		<div>ROUTB</div> <div>TTL/CMOS level, noninverting, always enabled receiver outputs.</div>	
	<div>INVALID</div> <div>Active low output that indicates if no valid RS-232 levels are present on any receiver input.</div>		<div>INVALID</div> <div>Active low output that indicates if no valid RS-232 levels are present on any receiver input.</div>	
	<div>EN</div> <div>Active low receiver enable control. doesn't disable ROUTB outputs.</div>		<div>EN</div> <div>Active low receiver enable control. doesn't disable ROUTB outputs.</div>	
	<div>SHDN</div> <div>Active low input to shut down transmitters and on-board power supply, to place device in low power mode.</div>		<div>SHDN</div> <div>Active low input to shut down transmitters and on-board power supply, to place device in low power mode.</div>	
	<div>FORCEOFF</div> <div>Active low to shut down transmitters and on-chip power supply. This overrides any automatic circuitry and FORCEON (See Table 2).</div>		<div>FORCEOFF</div> <div>Active low to shut down transmitters and on-chip power supply. This overrides any automatic circuitry and FORCEON (See Table 2).</div>	
	<div>FORCEON</div> <div>Active high input to override automatic powerdown circuitry thereby keeping transmitters active. (FORCEOFF must be high).</div>		<div>FORCEON</div> <div>Active high input to override automatic powerdown circuitry thereby keeping transmitters active. (FORCEOFF must be high).</div>	

for a single transmitter driving 1000pF and an RS-232 load at 250kbps. The static transmitters were also loaded with an RS-232 receiver.

FIGURE 8. TRANSMITTER OUTPUTS WHEN EXITING POWERDOWN

The ICL324X have been specifically designed to power a serial mouse while operating from low voltage supplies. Figure 9 shows the transmitter output voltages under increasing load current. The on-chip switching regulator ensures the transmitters will supply at least ±5V during worst case conditions (15mA for paralleled V+ transmitters, 7.3mA for single V- transmitter). The Automatic Powerdown feature does not work with a mouse, so FORCEOFF and FORCEON should be connected to VCC.

FIGURE 9. TRANSMITTER OUTPUT VOLTAGE vs LOAD CURRENT (PER TRANSMITTER, I.e., DOUBLE CURRENT AXIS FOR TOTAL VOUT+ CURRENT)

The ICL32XX maintain the RS-232 ±5V minimum transmitter output voltages even at high data rates. Figure 10 details a transmitter loopback test circuit, and Figure 11 illustrates the loopback test result at 120kbps. For this test, all transmitters were simultaneously driving RS-232 loads in parallel with 1000pF. Figure 12 shows the loopback results

FIGURE 10. TRANSMITTER LOOPBACK TEST CIRCUIT

5V/DIV

T1IN

T1OUT

R1OUT

5 μs/DIV

VCC = +3.3V

C1 - C4 = 0.1 μF

FIGURE 11. LOOPBACK TEST AT 120kbps

5V/DIV

T1IN

T1OUT

R1OUT

2 μs/DIV

VCC = +3.3V

C1 - C4 = 0.1 μF

FIGURE 12. LOOPBACK TEST AT 250kbps

DOSSIER TECHNIQUE

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SESSION 2008



February 1995

LMC567 Low Power Tone Decoder

General Description

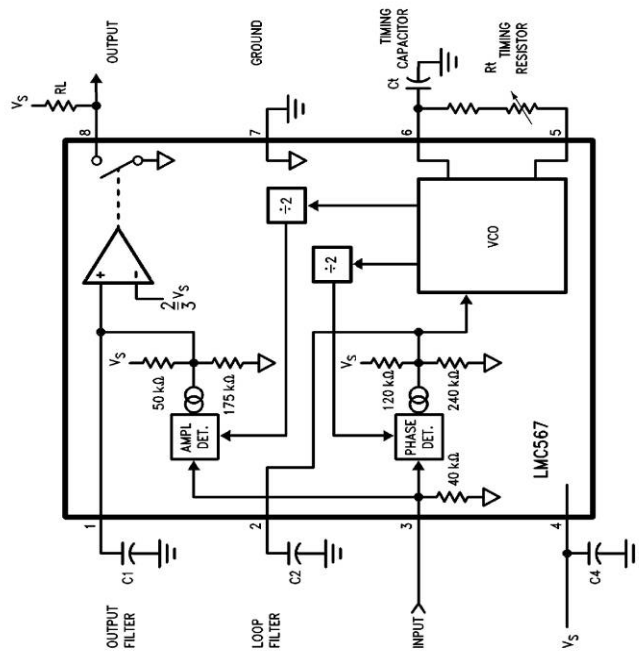
The LMC567 is a low power general purpose LMC567™ tone decoder which is functionally similar to the industry standard LM567. It consists of a twice frequency voltage-controlled oscillator (VCO) and quadrature dividers which establish the reference signals for phase and amplitude detectors. The phase detector and VCO form a phase-locked loop (PLL) which locks to an input signal frequency which is within the control range of the VCO. When the PLL is locked and the input signal amplitude exceeds an internally pre-set threshold, a switch to ground is activated on the output pin. External components set up the oscillator to run at twice the input frequency and determine the phase and amplitude filter time constants.

Features

- Functionally similar to LM567
- 2V to 9V supply voltage range
- Low supply current drain
- No increase in current with output activated
- Operates to 500 kHz input frequency
- High oscillator stability
- Ground-referenced input
- Hysteresis added to amplitude comparator
- Out-of-band signals and noise rejected
- 20 mA output current capability

LMC567™ is a trademark of National Semiconductor Corp.

Block Diagram (with External Components)



TL/H/6870-1

Order Number LMC567CMor LMC567CN  
See NS Package Number M08A or N08E

Absolute Maximum Ratings

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

- Input Voltage, Pin 3 2 V<sub>p-p</sub>
- Supply Voltage, Pin 4 10V
- Output Voltage, Pin 8 13V
- Voltage at All Other Pins V<sub>s</sub> to Gnd
- Output Current, Pin 8 30 mA
- Package Dissipation 500 mW
- Operating Temperature Range (T<sub>A</sub>) -25°C to +125°C

- Storage Temperature Range -55°C to +150°C
- Soldering Information Dual-In-Line Package Soldering (10 sec.) 260°C
- Small Outline Package Vapor Phase (60 sec.) 215°C
- Infrared (15 sec.) 220°C

See AN-450 "Surface Mounting Methods and Their Effect on Product Reliability" for other methods of soldering surface mount devices.

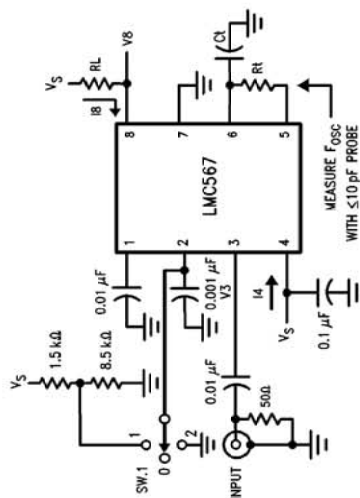
Electrical Characteristics

Test Circuit, T<sub>A</sub> = 25°C, V<sub>s</sub> = 5V, R<sub>IC1</sub> #2, Sw. 1 Pos. 0, and no input, unless otherwise noted.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
I <sub>4</sub>	Power Supply Current	R <sub>IC1</sub> #1, Quiescent or Activated	V <sub>s</sub> = 2V	0.3		
			V <sub>s</sub> = 5V	0.5	0.8	mA
			V <sub>s</sub> = 9V	0.8	1.3	
V <sub>3</sub>	Input D.C. Bias			0		mVdc
R <sub>3</sub>	Input Resistance			40		kΩ
I <sub>8</sub>	Output Leakage			1	100	nA
f <sub>0</sub>	Center Frequency, F <sub>osc</sub> ÷ 2	R <sub>IC1</sub> #2, Measure Oscillator Frequency and Divide by 2	V <sub>s</sub> = 2V	98		
			V <sub>s</sub> = 5V	92	103	kHz
			V <sub>s</sub> = 9V		105	
Δf <sub>0</sub>	Center Frequency Shift with Supply	$\frac{f_0 \Delta V - f_0 \Delta V}{7 f_0 \Delta V} \times 100$		1.0	2.0	%/V
V <sub>in</sub>	Input Threshold	Set Input Frequency Equal to f <sub>0</sub> Measured Above, Increase Input Level Until Pin 8 Goes Low.	V <sub>s</sub> = 2V	11	20	27
			V <sub>s</sub> = 5V	17	30	45
			V <sub>s</sub> = 9V		45	
ΔV <sub>in</sub>	Input Hysteresis	Starting at Input Threshold, Decrease Input Level Until Pin 8 goes High.		1.5		mVrms
V <sub>8</sub>	Output 'Sat' Voltage	Input Level > Threshold Choose R <sub>L</sub> for Specified I <sub>8</sub>	I <sub>8</sub> = 2 mA	0.06	0.15	Vdc
			I <sub>8</sub> = 20 mA		0.7	
L.D.B.W.	Largest Detection Bandwidth	Measure F <sub>osc</sub> with Sw. 1 in Pos. 0, 1, and 2; L.D.B.W. = $\frac{F_{oscP2} - F_{oscP1}}{F_{oscP0}} \times 100$	V <sub>s</sub> = 2V	7	11	15
			V <sub>s</sub> = 5V	11	14	17
			V <sub>s</sub> = 9V		15	
ABW	Bandwidth Skew	$Skew = \left( \frac{F_{oscP2} + F_{oscP1}}{2 F_{oscP0}} - 1 \right) \times 100$		0	±1.0	%
f <sub>max</sub>	Highest Center Freq.	R <sub>IC1</sub> #3, Measure Oscillator Frequency and Divide by 2		700		kHz
V <sub>in</sub>	Input Threshold at f <sub>max</sub>	Set Input Frequency Equal to f <sub>max</sub> measured Above, Increase Input Level Until Pin 8 goes Low.		35		mVrms

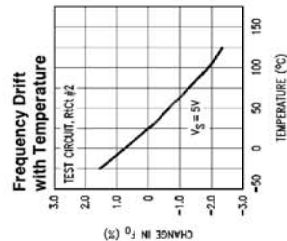
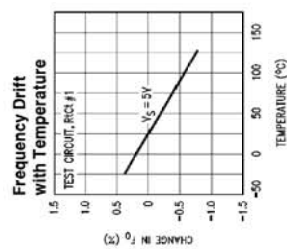
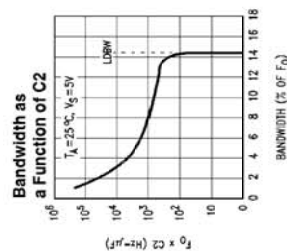
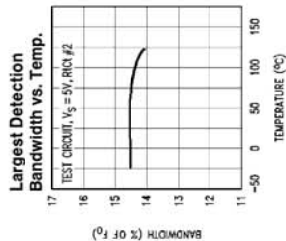
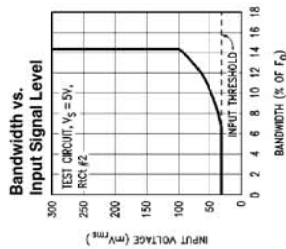
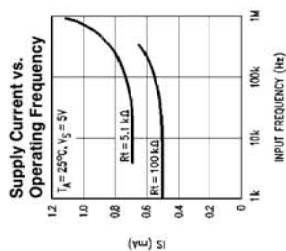
## Test Circuit

RICt	Rt	Ct
#1	100k	300 pF
#2	10k	300 pF
#3	5.1k	62 pF



TL/H/9670-2

## Typical Performance Characteristics



TL/H/9670-3

## Applications Information (refer to Block Diagram)

### GENERAL

The LMC567 low power tone decoder can be operated at supply voltages of 2V to 9V and at input frequencies ranging from 1 Hz up to 500 kHz.

The LMC567 can be directly substituted in most LM567 applications with the following provisions:

1. Oscillator timing capacitor Ct must be halved to double the oscillator frequency relative to the input frequency (See OSCILLATOR TIMING COMPONENTS).
2. Filter capacitors C1 and C2 must be reduced by a factor of 8 to maintain the same filter time constants.
3. The output current demanded of pin 8 must be limited to the specified capability of the LMC567.

### OSCILLATOR TIMING COMPONENTS

The voltage-controlled oscillator (VCO) on the LMC567 must be set up to run at twice the frequency of the input signal tone to be decoded. The center frequency of the VCO is set by timing resistor Rt and timing capacitor Ct connected to pins 5 and 6 of the IC. The center frequency as a function of Rt and Ct is given by:

$$F_{osc} \approx \frac{1}{1.4 R_t C_t}$$

Since this will cause an input tone of half  $F_{osc}$  to be decoded,

$$F_{input} \approx \frac{1}{2.8 R_t C_t}$$

This equation is accurate at low frequencies; however, above 50 kHz ( $F_{osc} = 100$  kHz), internal delays cause the actual frequency to be lower than predicted.

The choice of Rt and Ct will be a tradeoff between supply current and practical capacitor values. An additional supply current component is introduced due to Rt being switched to  $V_s$  every half cycle to charge Ct:

$$I_s \text{ due to } R_t = V_s / (4 R_t)$$

Thus the supply current can be minimized by keeping Rt as large as possible (see supply current vs. operating frequency curves). However, the desired frequency will dictate an RICt product such that increasing Rt will require a smaller Ct. Below Ct = 100 pF, circuit board stray capacitances begin to play a role in determining the oscillation frequency which ultimately limits the minimum Ct.

To allow for I.C. and component value tolerances, the oscillator timing components will require a trim. This is generally accomplished by using a variable resistor as part of Rt, although Ct could also be padded. The amount of initial frequency variation due to the LMC567 itself is given in the electrical specifications; the total trim range must also accommodate the tolerances of Rt and Ct.

### SUPPLY DECOUPLING

The decoupling of supply pin 4 becomes more critical at high supply voltages with high operating frequencies, requiring Ct to be placed as close as possible to pin 4.

### INPUT PIN

The input pin 3 is internally ground-referenced with a nominal 40 kΩ resistor. Signals which are already centered on 0V may be directly coupled to pin 3; however, any d.c. potential must be isolated via a coupling capacitor. Inputs of multiple LMC567 devices can be paralleled without individual d.c. isolation.

### LOOP FILTER

Pin 2 is the combined output of the phase detector and control input of the VCO for the phase-locked loop (PLL). Capacitor C2 in conjunction with the nominal 80 kΩ pin 2 internal resistance forms the loop filter.

For small values of C2, the PLL will have a fast acquisition time and the pull-in range will be set by the built in VCO frequency stops, which also determine the largest detection bandwidth (LDBW). Increasing C2 results in improved noise immunity at the expense of acquisition time, and the pull-in range will begin to become narrower than the LDBW (see Bandwidth as a Function of C2 curve). However, the maximum hold-in range will always equal the LDBW.

### OUTPUT FILTER

Pin 1 is the output of a negative-going amplitude detector which has a nominal 0 signal output of  $7/9 V_s$ . When the PLL is locked to the input, an increase in signal level causes the detector output to move negative. When pin 1 reaches  $2/3 V_s$  the output is activated (see OUTPUT PIN).

Capacitor C1 in conjunction with the nominal 40 kΩ pin 1 internal resistance forms the output filter. The size of C1 is a tradeoff between slow rate and carrier ripple at the output comparator. Low values of C1 produce the least delay between the input and output for tone burst applications, while larger values of C1 improve noise immunity.

Pin 1 also provides a means for shifting the input threshold higher or lower by connecting an external resistor to supply or ground. However, reducing the threshold using this technique increases sensitivity to pin 1 carrier ripple and also results in more part to part threshold variation.

### OUTPUT PIN

The output at pin 8 is an N-channel FET switch to ground which is activated when the PLL is locked and the input tone is of sufficient amplitude to cause pin 1 to fall below  $2/3 V_s$ . Apart from the obvious current component due to the external pin 8 load resistor, no additional supply current is required to activate the switch. The on resistance of the switch is inversely proportional to supply; thus the 'sat' voltage for a given output current will increase at lower supply levels.

PIC16F87X

10.1 USART Baud Rate Generator (BRG)

The BRG supports both the asynchronous and synchronous modes of the USART. It is a dedicated 8-bit baud rate generator. The SPBRG register controls the period of a free running 8-bit timer. In asynchronous mode, bit BRGH (TXSTA<2>) also controls the baud rate. In synchronous mode, bit BRGH is ignored. Table 10-1 shows the formula for computation of the baud rate for different USART modes which only apply in master mode (internal clock).

Given the desired baud rate and Fosc, the nearest integer value for the SPBRG register can be calculated using the formula in Table 10-1. From this, the error in baud rate can be determined.

It may be advantageous to use the high baud rate (BRGH = 1) even for slower baud clocks. This is because the  $F_{osc}/(16(X + 1))$  equation can reduce the baud rate error in some cases.

Writing a new value to the SPBRG register causes the BRG timer to be reset (or cleared). This ensures the BRG does not wait for a timer overflow before outputting the new baud rate.

10.1.1 SAMPLING

The data on the RC7/RX/DT pin is sampled three times by a majority detect circuit to determine if a high or a low level is present at the RX pin.

TABLE 10-1: BAUD RATE FORMULA

SYNC	BRGH = 0 (Low Speed)	BRGH = 1 (High Speed)
0	(Asynchronous) Baud Rate = $F_{osc}/(64(X+1))$	Baud Rate = $F_{osc}/(16(X+1))$
1	(Synchronous) Baud Rate = $F_{osc}/(4(X+1))$	NA

X = value in SPBRG (0 to 255)

TABLE 10-2: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
18h	RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
99h	SPBRG	Baud Rate Generator Register									

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used by the BRG.

PIC16F87X

TABLE 10-3: BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 0)

BAUD RATE (K)	Fosc = 20 MHz			Fosc = 16 MHz			Fosc = 10 MHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	-	-	-	-	-	-	-	-	-
1.2	1.221	1.75	255	1.202	0.17	207	1.202	0.17	129
2.4	2.404	0.17	129	2.404	0.17	103	2.404	0.17	64
9.6	9.766	1.73	31	9.615	0.16	25	9.766	1.73	15
19.2	19.531	1.72	15	19.231	0.16	12	19.531	1.72	7
28.8	31.250	8.51	9	27.778	3.55	8	31.250	8.51	4
33.6	34.722	3.34	8	35.714	0.29	6	31.250	6.99	4
57.6	62.500	8.51	4	62.500	8.51	3	52.083	9.58	2
HIGH	1.221	-	255	0.977	-	255	0.610	-	255
LOW	312.500	-	0	250.000	-	0	156.250	-	0

BAUD RATE (K)	Fosc = 4 MHz			Fosc = 3.6864 MHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	0.300	0	207	0.301	0.33	185
1.2	1.202	0.17	51	1.216	1.33	46
2.4	2.404	0.17	25	2.432	1.33	22
9.6	8.929	6.99	6	9.322	2.90	5
19.2	20.833	8.51	2	18.643	2.90	2
28.8	31.250	8.51	1	-	-	-
33.6	-	-	-	-	-	-
57.6	62.500	8.51	0	55.930	2.90	0
HIGH	0.244	-	255	0.218	-	255
LOW	62.500	-	0	55.930	-	0

TABLE 10-4: BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 1)

BAUD RATE (K)	Fosc = 20 MHz			Fosc = 16 MHz			Fosc = 10 MHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	-	-	-	-	-	-	-	-	-
1.2	-	-	-	-	-	-	-	-	-
2.4	-	-	-	-	-	-	2.441	1.71	255
9.6	9.615	0.16	129	9.615	0.16	103	9.615	0.16	64
19.2	19.231	0.16	64	19.231	0.16	51	19.531	1.72	31
28.8	29.070	0.94	42	29.412	2.13	33	28.409	1.36	21
33.6	33.784	0.55	36	33.333	0.79	29	32.895	2.10	18
57.6	59.524	3.34	20	58.824	2.13	16	56.818	1.36	10
HIGH	4.883	-	255	3.906	-	255	2.441	-	255
LOW	1250.000	-	0	1000.000	-	0	625.000	-	0

BAUD RATE (K)	Fosc = 4 MHz			Fosc = 3.6864 MHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	-	-	-	-	-	-
1.2	1.202	0.17	207	1.203	0.25	185
2.4	2.404	0.17	103	2.406	0.25	92
9.6	9.615	0.16	25	9.727	1.32	22
19.2	19.231	0.16	12	18.643	2.90	11
28.8	27.798	3.55	8	27.965	2.90	7
33.6	35.714	6.29	6	31.960	4.88	6
57.6	62.500	8.51	3	55.930	2.90	3
HIGH	0.977	-	255	0.874	-	255
LOW	250.000	-	0	273.722	-	0

## PIC16F87X

### 11.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

The Analog-to-Digital (A/D) Converter module has five inputs for the 28-pin devices and eight for the other devices.

The analog input charges a sample and hold capacitor. The output of the sample and hold capacitor is the input into the converter. The converter then generates a digital result of this analog level via successive approximation. The A/D conversion of the analog input signal results in a corresponding 10-bit digital number. The A/D module has high and low voltage reference input that is software selectable to some combination of V<sub>DD</sub>, V<sub>SS</sub>, RA2 or RA3.

The A/D converter has a unique feature of being able to operate while the device is in SLEEP mode. To operate in sleep, the A/D clock must be derived from the A/D's internal RC oscillator.

The A/D module has four registers. These registers are:

- A/D Result High Register (ADRESH)
- A/D Result Low Register (ADRESL)
- A/D Control Register0 (ADCON0)
- A/D Control Register1 (ADCON1)

The ADCON0 register, shown in Register 11-1, controls the operation of the A/D module. The ADCON1 register, shown in Register 11-2, configures the functions of the port pins. The port pins can be configured as analog inputs (RA3 can also be the voltage reference) or as digital I/O.

Additional information on using the A/D module can be found in the PICmicro™ Mid-Range MCU Family Reference Manual (DS33023).

REGISTER 11-1: ADCON0 REGISTER (ADDRESS: 1Fh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0
ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/DONE	—	ADON
bit7							bit0
bit 7-6: <b>ADCS1:ADCS0: A/D Conversion Clock Select bits</b> 00 = Fosc/2 01 = Fosc/8 10 = Fosc/32 11 = Frc (clock derived from an RC oscillation)							
bit 5-3: <b>CHS2:CHS0: Analog Channel Select bits</b> 000 = channel 0, (RA0/AN0) 001 = channel 1, (RA1/AN1) 010 = channel 2, (RA2/AN2) 011 = channel 3, (RA3/AN3) 100 = channel 4, (RA5/AN4) 101 = channel 5, (RE0/AN5) <sup>(1)</sup> 110 = channel 6, (RE1/AN6) <sup>(1)</sup> 111 = channel 7, (RE2/AN7) <sup>(1)</sup>							
bit 2: <b>GO/DONE: A/D Conversion Status bit</b> If ADON = 1 1 = A/D conversion in progress (setting this bit starts the A/D conversion) 0 = A/D conversion not in progress (This bit is automatically cleared by hardware when the A/D conversion is complete)							
bit 1: <b>Unimplemented</b> Read as '0'							
bit 0: <b>ADON: A/D On bit</b> 1 = A/D converter module is operating 0 = A/D converter module is shutdown and consumes no operating current							
<b>Note 1:</b> These channels are not available on the 28-pin devices.							

R = Readable bit  
W = Writable bit  
U = Unimplemented bit, read as '0'  
-n = Value at POR reset

## PIC16F87X

The ADRESH:ADRESL registers contain the 10-bit result of the A/D conversion. When the A/D conversion is complete, the result is loaded into this A/D result register pair, the GO/DONE bit (ADCON0<2>) is cleared and the A/D interrupt flag bit ADIF is set. The block diagram of the A/D module is shown in Figure 11-1.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as inputs. To determine sample time, see Section 11.1. After this acquisition time has elapsed, the A/D conversion can be started. The following steps should be followed for doing an A/D conversion:

1. Configure the A/D module:
    - Configure analog pins / voltage reference / and digital I/O (ADCON1)
    - Select A/D input channel (ADCON0)
    - Select A/D conversion clock (ADCON0)
    - Turn on A/D module (ADCON0)
  2. Configure A/D interrupt (if desired):
    - Clear ADIF bit
    - Set ADIE bit
    - Set GIE bit
  3. Wait the required acquisition time.
  4. Start conversion:
    - Set GO/DONE bit (ADCON0)
  5. Wait for A/D conversion to complete, by either:
    - Polling for the GO/DONE bit to be cleared
- OR
6. Waiting for the A/D interrupt
    - Read A/D Result register pair (ADRESH:ADRESL), clear bit ADIF if required.
  7. For next conversion, go to step 1 or step 2 as required. The A/D conversion time per bit is defined as T<sub>AD</sub>. A minimum wait of 2T<sub>AD</sub> is required before next acquisition starts.

## LIBRAIRIES

- **USART**

## Hardware Peripheral Functions

---

### OpenUSART Open1USART Open2USART

---

**Function:** Configure the specified USART module.

**Include:** `usart.h`

**Prototype:**

```
void OpenUSART( unsigned char config
                unsigned int spbrg ;
void Open1USART( unsigned char config
                unsigned int spbrg ;
void Open2USART( unsigned char config
                unsigned int spbrg ;
```

**Arguments:** *config*  
A bitmask that is created by performing a bitwise AND operation ('&') with a value from each of the categories listed below. These values are defined in the file `usart.h`

**Interrupt on Transmission:**

USART_TX_INT_ON	Transmit interrupt ON
USART_TX_INT_OFF	Transmit interrupt OFF

**Interrupt on Receipt:**

USART_RX_INT_ON	Receive interrupt ON
USART_RX_INT_OFF	Receive interrupt OFF

**USART Mode:**

USART_ASYNC_MODE	Asynchronous Mode
USART_SYNC_MODE	Synchronous Mode

**Transmission Width:**

USART_EIGHT_BIT	8-bit transmit/receive
USART_NINE_BIT	9-bit transmit/receive

**Slave/Master Select\*:**

USART_SYNC_SLAVE	Synchronous Slave mode
USART_SYNC_MASTER	Synchronous Master mode

**Reception mode:**

USART_SINGLE_RX	Single reception
USART_CONT_RX	Continuous reception

**Baud rate:**

USART_BRGH_HIGH	High baud rate
USART_BRGH_LOW	Low baud rate

\* Applies to Synchronous mode only

***spbrg***

This is the value that is written to the baud rate generator register which determines the baud rate at which the USART operates. The formulas for baud rate are:

Asynchronous mode, high speed:

$$F_{SC} / (16 * (spbrg + 1))$$

Asynchronous mode, low speed:

$$F_{SC} / (64 * (spbrg + 1))$$

Synchronous mode:

$$F_{SC} / (4 * (spbrg + 1))$$

Where  $F_{SC}$  is the oscillator frequency.

**Remarks:** This function configures the USART module according to the specified configuration options.

OpenUSART should be used on parts with a single USART peripheral. Open1USART and Open2USART should be used on parts with multiple USART peripherals.

**File Name:** `uopen.c`  
`u1open.c`  
`u2open.c`



## Chapter 2. Hardware Peripheral Functions

### 2.1 INTRODUCTION

This chapter documents the hardware peripheral functions found in the processor-specific libraries. The source code for all of these functions is included with MPLAB C18 in the `src\traditional\pmc` and `src\extended\pmc` subdirectories of the compiler installation.

See the *MPLASM™ User's Guide with MPLINK™ and MPLIB™* (DS33014) for more information about managing libraries using the MPLIB librarian.

The following peripherals are supported by MPLAB C18 library routines:

- A/D Converter (Section 2.2 "A/D Converter Functions")
- Input Capture (Section 2.3 "Input Capture Functions")
- I<sup>2</sup>C™ (Section 2.4 "I<sup>2</sup>C™ Functions")
- I/O Ports (Section 2.5 "I/O Port Functions")
- Microwire (Section 2.6 "Microwire Functions")
- Pulse-Width Modulation (PWM) (Section 2.7 "Pulse-Width Modulation Functions")
- SPI™ (Section 2.8 "SPI™ Functions")
- Timer (Section 2.9 "Timer Functions")
- USART (Section 2.10 "USART Functions")

### 2.2 A/D CONVERTER FUNCTIONS

The A/D peripheral is supported with the following functions:

TABLE 2-1: A/D CONVERTER FUNCTIONS

Function	Description
BusyADC	Is A/D converter currently performing a conversion?
CloseADC	Disable the A/D converter.
ConvertADC	Start an A/D conversion.
OpenADC	Configure the A/D converter.
ReadADC	Read the results of an A/D conversion.
SetChanADC	Select A/D channel to be used.

## MPLAB® C18 C Compiler Libraries

### 2.2.1 Function Descriptions

#### BusyADC

**Function:** Is the A/D converter currently performing a conversion?  
**Include:** `adc.h`  
**Prototype:** `char BusyADC( void );`  
**Remarks:** This function indicates if the A/D peripheral is in the process of converting a value.  
**Return Value:** 1 if the A/D peripheral is performing a conversion.  
0 if the A/D peripheral isn't performing a conversion.  
**File Name:** `adcbusy.c`

#### CloseADC

**Function:** Disable the A/D converter.  
**Include:** `adc.h`  
**Prototype:** `void CloseADC( void );`  
**Remarks:** This function disables the A/D converter and A/D interrupt mechanism.  
**File Name:** `adcclose.c`

#### ConvertADC

**Function:** Starts the A/D conversion process.  
**Include:** `adc.h`  
**Prototype:** `void ConvertADC( void );`  
**Remarks:** This function starts an A/D conversion. The `BusyADC()` function may be used to detect completion of the conversion.  
**File Name:** `adcconv.c`

#### OpenADC

##### PIC18CXX2, PIC18FXX2, PIC18FXX8, PIC18FXX39

**Function:** Configure the A/D converter.  
**Include:** `adc.h`  
**Prototype:** `void OpenADC( unsigned char config, unsigned char config2 );`

##### Arguments:

**config**  
A bitmask that is created by performing a bitwise AND operation ('&') with a value from each of the categories listed below. These values are defined in the file `adc.h`.

##### A/D clock source:

`ADC_FOSC_2` `FOSC / 2`  
`ADC_FOSC_4` `FOSC / 4`  
`ADC_FOSC_8` `FOSC / 8`  
`ADC_FOSC_16` `FOSC / 16`  
`ADC_FOSC_32` `FOSC / 32`  
`ADC_FOSC_64` `FOSC / 64`  
`ADC_FOSC_RC` Internal RC Oscillator

##### A/D result justification:

`ADC_RIGHT_JUST` Result in Least Significant bits  
`ADC_LEFT_JUST` Result in Most Significant bits



Hardware Peripheral Functions

OpenADC

PIC18CXX2, PIC18FXX2, PIC18FXX8, PIC18FXX39 (Continued)

A/D voltage reference source:

ADC\_8ANA\_0REF VREF+=VDD, VREF-=VSS,  
All analog channels  
AN3=VREF+, All analog  
channels except AN3  
ADC\_7ANA\_1REF AN3=VREF+, AN2=VREF  
ADC\_6ANA\_2REF VREF+=VDD, VREF-=VSS  
ADC\_6ANA\_0REF AN3=VREF+, VREF-=VSS  
ADC\_5ANA\_1REF VREF+=VDD, VREF-=VSS  
ADC\_5ANA\_0REF AN3=VREF+, AN2=VREF-  
ADC\_4ANA\_2REF AN3=VREF+  
ADC\_4ANA\_1REF AN3=VREF+, AN2=VREF-  
ADC\_3ANA\_2REF VREF+=VDD, VREF-=VSS  
ADC\_3ANA\_0REF AN3=VREF+, AN2=VREF-  
ADC\_2ANA\_2REF AN3=VREF+  
ADC\_2ANA\_1REF AN3=VREF+, AN2=VREF-  
ADC\_1ANA\_2REF AN0=A  
ADC\_1ANA\_0REF AN0 is analog input  
ADC\_0ANA\_0REF All digital I/O

config2

A bitmask that is created by performing a bitwise AND operation ('&') with a value from each of the categories listed below. These values are defined in the file adc.h.

Channel:

ADC\_CH0 Channel 0  
ADC\_CH1 Channel 1  
ADC\_CH2 Channel 2  
ADC\_CH3 Channel 3  
ADC\_CH4 Channel 4  
ADC\_CH5 Channel 5  
ADC\_CH6 Channel 6  
ADC\_CH7 Channel 7

A/D Interrupts:

ADC\_INT\_ON Interrupts enabled  
ADC\_INT\_OFF Interrupts disabled

**Remarks:** This function resets the A/D peripheral to the POR state and configures the A/D-related Special Function Registers (SFRs) according to the options specified.

**File Name:** adopen.c

**Code Example:** OpenADC ( ADC\_FOSC\_32 &  
ADC\_RIGHT\_JUST &  
ADC\_1ANA\_0REF, &  
ADC\_CH0 &  
ADC\_INT\_OFF );

Hardware Peripheral Functions

SetChanADC

**Function:** Select the channel used as input to the A/D converter.

**Include:** adc.h

**Prototype:** void SetChanADC( unsigned char channel );

**Arguments:** channel

One of the following values (defined in adc.h):

ADC\_CH0 Channel 0  
ADC\_CH1 Channel 1  
ADC\_CH2 Channel 2  
ADC\_CH3 Channel 3  
ADC\_CH4 Channel 4  
ADC\_CH5 Channel 5  
ADC\_CH6 Channel 6  
ADC\_CH7 Channel 7  
ADC\_CH8 Channel 8  
ADC\_CH9 Channel 9  
ADC\_CH10 Channel 10  
ADC\_CH11 Channel 11

**Remarks:** Selects the pin that will be used as input to the A/D converter.

**File Name:** adcsetch.c

**Code Example:** SetChanADC( ADC\_CH0 );

ReadADC

**Function:** Read the result of an A/D conversion.

**Include:** adc.h

**Prototype:** int ReadADC( void );

**Remarks:** This function reads the 16-bit result of an A/D conversion.

**Return Value:** This function returns the 16-bit signed result of the A/D conversion. Based on the configuration of the A/D converter (e.g., using the OpenADC() function), the result will be contained in the Least Significant or Most Significant bits of the 16-bit result.

**File Name:** adcread.c

- I2C

## Hardware Peripheral Functions

### OpenI2C

#### OpenI2C1

#### OpenI2C2

<b>Function:</b>	Configure the SSPx module.										
<b>Include:</b>	i2c.h										
<b>Prototype:</b>	<pre>void OpenI2C( unsigned char <i>sync_mode</i>,               unsigned char <i>slew</i> ); void OpenI2C1( unsigned char <i>sync_mode</i>,                unsigned char <i>slew</i> ); void OpenI2C2( unsigned char <i>sync_mode</i>,                unsigned char <i>slew</i> );</pre>										
<b>Arguments:</b>	<p><b><i>sync_mode</i></b>            One of the following values, defined in i2c.h</p> <table> <tr> <td>SLAVE_7</td><td>I<sup>2</sup>C Slave mode, 7-bit address</td></tr> <tr> <td>SLAVE_10</td><td>I<sup>2</sup>C Slave mode, 10-bit address</td></tr> <tr> <td>MASTER</td><td>I<sup>2</sup>C Master mode</td></tr> </table> <p><b><i>slew</i></b>            One of the following values, defined in i2c.h</p> <table> <tr> <td>SLEW_OFF</td><td>Slew rate disabled for 100 kHz mode</td></tr> <tr> <td>SLEW_ON</td><td>Slew rate enabled for 400 kHz mode</td></tr> </table>	SLAVE_7	I <sup>2</sup> C Slave mode, 7-bit address	SLAVE_10	I <sup>2</sup> C Slave mode, 10-bit address	MASTER	I <sup>2</sup> C Master mode	SLEW_OFF	Slew rate disabled for 100 kHz mode	SLEW_ON	Slew rate enabled for 400 kHz mode
SLAVE_7	I <sup>2</sup> C Slave mode, 7-bit address										
SLAVE_10	I <sup>2</sup> C Slave mode, 10-bit address										
MASTER	I <sup>2</sup> C Master mode										
SLEW_OFF	Slew rate disabled for 100 kHz mode										
SLEW_ON	Slew rate enabled for 400 kHz mode										
<b>Remarks:</b>	OpenI2Cx resets the SSPx module to the POR state and then configures the module for Master/Slavemode and the selected slew rate.										
<b>File Name:</b>	i2c_open.c i2c1open.c i2c2open.c										
<b>Code Example:</b>	OpenI2C(MASTER, SLEW_ON);										

### EEByteWrite



<b>Function :</b>	Write a single byte to the I2C bus
<b>Include :</b>	i2c.h
<b>Prototype :</b>	<pre>unsigned char EEByteWrite(     Unsigned char <b>control</b>,     Unsigned char <b>addressH</b>,     Unsigned char <b>addressL</b>,     Unsigned char <b>data</b> );</pre>
<b>Arguments</b>	<p><b>control</b> : EEPROM control/ bus device select address byte.</p> <p><b>addressH &amp; addressL</b>: EEPROM internal address location.</p> <p><b>data</b> : Data to write to EEPROM address specified in function parameter address</p>



STL

L4931  
SERIES

VERY LOW DROP  
VOLTAGE REGULATORS WITH INHIBIT



TO-220

PPAK

SO-8

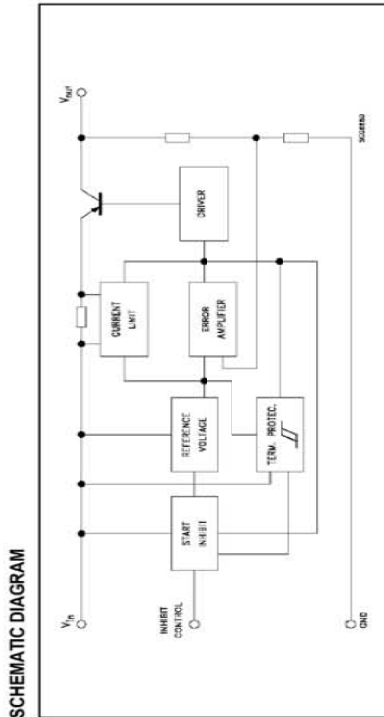
DPAK

- VERY LOW DROPOUT VOLTAGE (0.4V)
- VERY LOW QUIESCENT CURRENT (TYP. 50 µA IN OFF MODE, 600µA IN ON MODE)
- OUTPUT CURRENT UP TO 250 mA
- LOGIC-CONTROLLED ELECTRONIC SHUTDOWN
- OUTPUT VOLTAGES OF 1.25; 1.5; 2.5; 2.7; 3; 3.3; 3.5; 4; 4.5; 4.7; 5; 5.2; 5.5; 6; 8; 12V
- INTERNAL CURRENT AND THERMAL LIMIT
- ONLY 2.2µF FOR STABILITY
- AVAILABLE IN ± 1% (AB) OR 2% (C) SELECTION AT 25 °C
- SUPPLY VOLTAGE REJECTION: 70db TYP. FOR 5V VERSION
- TEMPERATURE RANGE: -40 TO 125 °C

**DESCRIPTION**

The L4931 series are very Low Drop regulators available in TO-220, SO-8, DPAK, PPAK and TO-92 packages and in a wide range of output voltages.

The very Low Drop voltage (0.4V) and the very low quiescent current make them particularly suitable for Low Noise, Low Power applications and specially in battery powered systems.

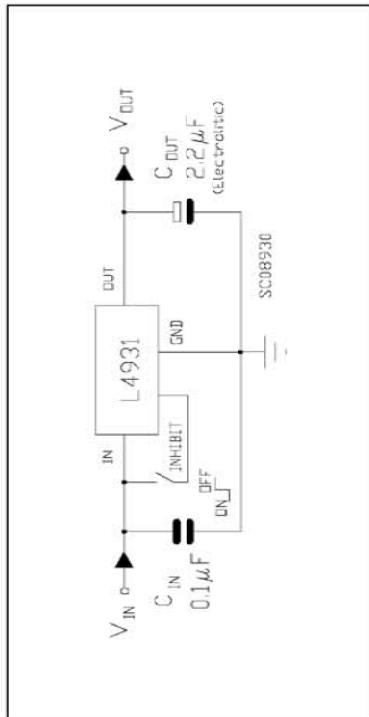


L4931 SERIES

ORDERING NUMBERS				Output Voltage
TO-220	SO-8	PPAK	DPAK	
L4931CV12 (*)	L4931CD12 (*)	L4931CPT12 (*)	L4931ABDT12 (*)	1.25 V
L4931ABV12 (*)	L4931ABD12 (*)	L4931ABPT12 (*)	L4931ABDT12 (*)	1.25 V
L4931CV15 (*)	L4931CD15 (*)	L4931CPT15 (*)	L4931ABDT15 (*)	1.5 V
L4931ABV15 (*)	L4931ABD15 (*)	L4931ABPT15 (*)	L4931ABDT15 (*)	1.5 V
L4931CV25 (*)	L4931CD25 (*)	L4931CPT25 (*)	L4931ABDT25 (*)	2.5 V
L4931ABV25 (*)	L4931ABD25 (*)	L4931ABPT25 (*)	L4931ABDT25 (*)	2.5 V
L4931CV27 (*)	L4931CD27 (*)	L4931CPT27 (*)	L4931ABDT27 (*)	2.7 V
L4931ABV27 (*)	L4931ABD27 (*)	L4931ABPT27 (*)	L4931ABDT27 (*)	2.7 V
L4931CV30 (*)	L4931CD30 (*)	L4931CPT30 (*)	L4931ABDT30 (*)	3 V
L4931ABV30 (*)	L4931ABD30 (*)	L4931ABPT30 (*)	L4931ABDT30 (*)	3 V
L4931CV33 (*)	L4931CD33 (*)	L4931CPT33 (*)	L4931ABDT33 (*)	3.3 V
L4931ABV33 (*)	L4931ABD33 (*)	L4931ABPT33 (*)	L4931ABDT33 (*)	3.3 V
L4931CV35 (*)	L4931CD35 (*)	L4931CPT35 (*)	L4931ABDT35 (*)	3.5 V
L4931ABV35 (*)	L4931ABD35 (*)	L4931ABPT35 (*)	L4931ABDT35 (*)	3.5 V
L4931CV40 (*)	L4931CD40 (*)	L4931CPT40 (*)	L4931ABDT40 (*)	4 V
L4931ABV40 (*)	L4931ABD40 (*)	L4931ABPT40 (*)	L4931ABDT40 (*)	4 V
L4931CV45 (*)	L4931CD45 (*)	L4931CPT45 (*)	L4931ABDT45 (*)	4.5 V
L4931ABV45 (*)	L4931ABD45 (*)	L4931ABPT45 (*)	L4931ABDT45 (*)	4.5 V
L4931CV47 (*)	L4931CD47 (*)	L4931CPT47 (*)	L4931ABDT47 (*)	4.75 V
L4931ABV47 (*)	L4931ABD47 (*)	L4931ABPT47 (*)	L4931ABDT47 (*)	4.75 V
L4931CV50 (*)	L4931CD50 (*)	L4931CPT50 (*)	L4931ABDT50 (*)	5 V
L4931ABV50 (*)	L4931ABD50 (*)	L4931ABPT50 (*)	L4931ABDT50 (*)	5 V
L4931CV52 (*)	L4931CD52 (*)	L4931CPT52 (*)	L4931ABDT52 (*)	5.2 V
L4931ABV52 (*)	L4931ABD52 (*)	L4931ABPT52 (*)	L4931ABDT52 (*)	5.2 V
L4931CV55 (*)	L4931CD55 (*)	L4931CPT55 (*)	L4931ABDT55 (*)	5.5 V
L4931ABV55 (*)	L4931ABD55 (*)	L4931ABPT55 (*)	L4931ABDT55 (*)	5.5 V
L4931CV60 (*)	L4931CD60 (*)	L4931CPT60 (*)	L4931ABDT60 (*)	6 V
L4931ABV60 (*)	L4931ABD60 (*)	L4931ABPT60 (*)	L4931ABDT60 (*)	6 V
L4931CV80 (*)	L4931CD80 (*)	L4931CPT80 (*)	L4931ABDT80 (*)	8 V
L4931ABV80 (*)	L4931ABD80 (*)	L4931ABPT80 (*)	L4931ABDT80 (*)	8 V
L4931CV120 (*)	L4931CD120 (*)	L4931CPT120 (*)	L4931ABDT120 (*)	12 V
L4931ABV120 (*)	L4931ABD120 (*)	L4931ABPT120 (*)	L4931ABDT120 (*)	12 V

(\*) Available on request

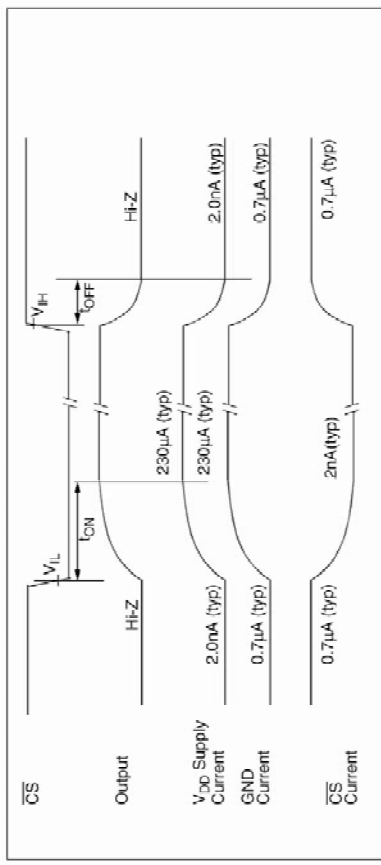
TEST CIRCUITS



MCP601/602/603/604

3.4 The Chip Select Option of the MCP603

The MCP603 is a single amplifier with a Chip Select option. When CS is pulled high the supply current drops to 0.7µA (typ), which is pulled through the CS pin to V<sub>SS</sub>. In this state, the amplifier is put into a high impedance state. By pulling CS low or letting the pin float, the amplifier is enabled. Figure 3-8 shows the cutput voltage and supply current response to a CS pulse.



MCP60X PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

MCP60X — X / X

Package: P = Plastic DIP (300 mil Body), 8-lead and 14-lead  
SN = Plastic SOIC (150 mil Body), 8-lead  
SL = Plastic SOIC (150 mil Body), 14-lead  
ST = Plastic TSSOP, 8-lead and 14-lead  
OT = Plastic SOT23, 5-lead

Temperature Range: I = -40°C to +85°C

Device: MCP601 = Single Operational Amplifier  
MCP601T = Single Operational Amplifier (Tape and Reel-SOIC/TSSOP/SOT23-5)  
MCP602 = Dual Operational Amplifier  
MCP602T = Dual Operational Amplifier (Tape and Reel-SOIC/TSSOP)  
MCP603 = Single Operational Amplifier w/CS Function  
MCP603T = Single Operational Amplifier w/CS Function (Tape and Reel-SOIC/TSSOP)  
MCP604 = Quad Operational Amplifier  
MCP604T = Quad Operational Amplifier (Tape and Reel-SOIC/TSSOP)

Sales and Support

**Data Sheets**  
Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:  
1. Your local Microchip sales office  
2. The Microchip Corporate Literature Center U.S. FAX: (480) 786-7277  
3. The Microchip Worldwide Site ([www.microchip.com](http://www.microchip.com))  
Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.  
New Customer Notification System  
Register on our web site ([www.microchip.com/cn](http://www.microchip.com/cn)) to receive the most current information on our products.



MCP601/602/603/604  
2.7V to 5.5V Single Supply CMOS Op Amps

FEATURES

- Specifications rated from 2.7V to 5.5V supplies
- Rail-to-rail swing at output
- Common-mode input voltage range goes 0.3V below ground, making these amplifiers ideal for single supply operation.
- These devices are appropriate for low-power battery operated circuits due to the low quiescent current, for A/D Converter driver amplifiers because of their wide bandwidth, or for anti-aliasing filters by virtue of their low input bias current.
- The MCP601, MCP602 and MCP603 are available in standard 8-lead PDIP, SOIC and TSSOP packages. The MCP601 is also available in the SOT23-5 package. The quad MCP604 is offered in 14-lead PDIP, SOIC and TSSOP packages. PDIP and SOIC packages are fully specified from -40°C to +85°C with power supplies from 2.7V to 5.5V.

APPLICATIONS

- Portable Equipment
- A/D Converter Driver
- Photodiode Pre-amps
- Analog Filters
- Data Acquisition
- Notebooks and PDAs
- Sensor Interface

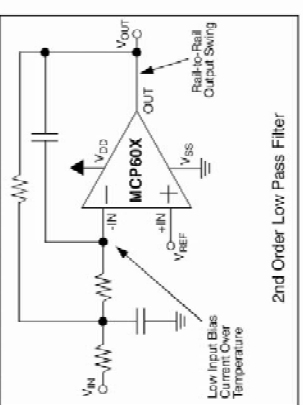
AVAILABLE TOOLS

- Spice Macro models (at [www.microchip.com](http://www.microchip.com))
  - FilterLab™ Software (at [www.microchip.com](http://www.microchip.com))
- © 2000 Microchip Technology Inc.

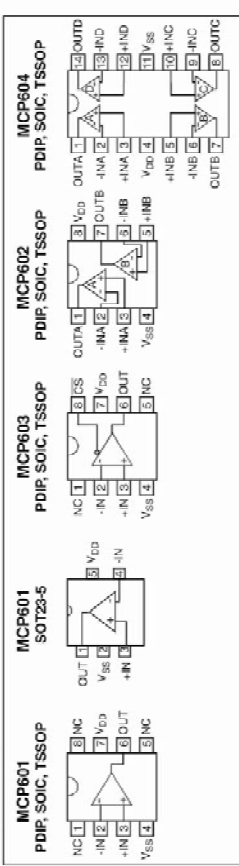
DESCRIPTION

The Microchip Technology Inc. MCP601/602/603/604 family of low-power operational amplifiers are offered in single (MCP601), single with a Chip Select pin feature (MCP603), dual (MCP602) and quad (MCP604) configurations. These operational amplifiers (op amps) utilize an advanced CMOS technology, which provides low bias current, high speed operation, high open-loop gain and rail-to-rail output swing. This product offering oper-

TYPICAL APPLICATION



PACKAGES



Features

- 64K bit Ferroelectric Nonvolatile RAM

  - Organized as 8,192 x 8 bits
  - Unlimited Read/Write Cycles
  - 10 year Data Retention
  - NoDelay™ Writes
  - Advanced High-Reliability Ferroelectric Process
- Low Power Operation

  - True 2.7V-3.6V Operation
  - 75  $\mu$ A Active Current (100 kHz)
  - 1  $\mu$ A Standby Current
- Industry Standard Configuration

  - Industrial Temperature -40° C to +85° C
  - 8-pin SOIC

Fast Two-wire Serial Interface

- Up to 1 MHz maximum bus frequency
- Direct hardware replacement for EEPROM
- Supports legacy timing for 100 kHz & 400 kHz

Description

The FM24CL64 is a 64-kilobit nonvolatile memory employing an advanced ferroelectric process. A ferroelectric random access memory or FRAM is nonvolatile and performs reads and writes like a RAM. It provides reliable data retention for 10 years while eliminating the complexities, overhead, and system level reliability problems caused by EEPROM and other nonvolatile memories.

The FM24CL64 performs write operations at bus speed. No write delays are incurred. The next bus cycle may commence immediately without the need for data polling. In addition, the product offers write endurance orders of magnitude higher than EEPROM. Also, FRAM exhibits much lower power during writes than EEPROM since write operations do not require an internally elevated power supply voltage for write circuits.

These capabilities make the FM24CL64 ideal for nonvolatile memory applications requiring frequent or rapid writes. Examples range from data collection where the number of write cycles may be critical, to demanding industrial controls where the long write time of EEPROM can cause data loss. The combination of features allows more frequent data writing with less overhead for the system.

The FM24CL64 provides substantial benefits to users of serial EEPROM, yet these benefits are available in a hardware drop-in replacement. The FM24CL64 is provided in industry standard 8-pin surface mount package using a familiar two-wire protocol. It is guaranteed over an industrial temperature range of -40°C to +85°C.

This product conforms to specifications per the terms of the Ramtron standard warranty. Production processing does not necessarily include testing of all parameters.

Ramtron International Corporation  
1850 Ramtron Drive, Colorado Springs, CO 80921  
(800) 545-FRAM, (719) 481-7000, Fax (719) 481-7058  
[www.ramtron.com](http://www.ramtron.com)

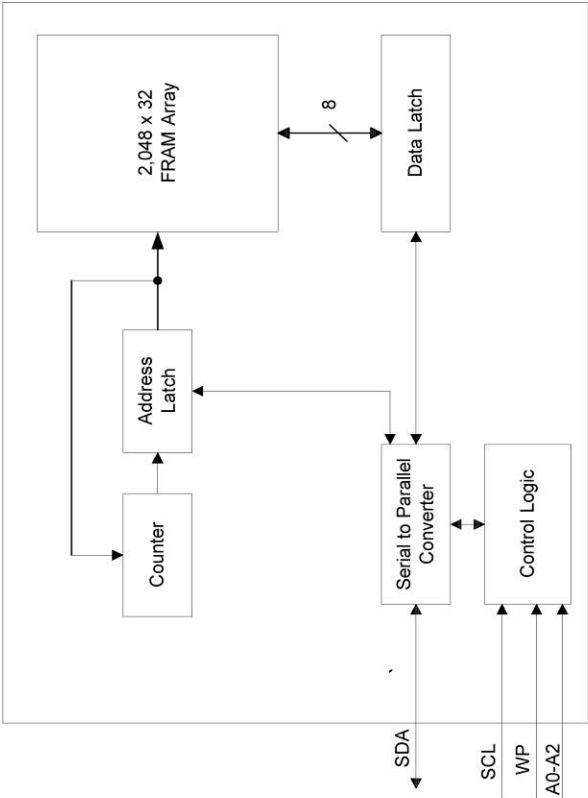


Figure 1. FM24CL64 Block Diagram

Pin Description

Pin Name	Type	Pin Description
A0-A2	Input	Address 0-2. These pins are used to select one of up to 8 devices of the same type on the same two-wire bus. To select the device, the address value on the three pins must match the corresponding bits contained in the device address. The address pins are pulled down internally.
SDA	I/O	Serial Data Address. This is a bi-directional line for the two-wire interface. It is open-drain and is intended to be wire-OR'd with other devices on the two-wire bus. The input buffer incorporates a Schmitt trigger for noise immunity and the output driver includes slope control for falling edges. A pull-up resistor is required.
SCL	Input	Serial Clock. The serial clock line for the two-wire interface. Data is clocked out of the part on the falling edge, and in on the rising edge. The SCL input also incorporates a Schmitt trigger input for noise immunity.
WP	Input	Write Protect. When tied to VDD, addresses in the entire memory map will be write-protected. When WP is connected to ground, all addresses may be written. This pin is pulled down internally.
VDD	Supply	Supply Voltage: 2.7V to 3.6V
VSS	Supply	Ground

## Memory Operation

The FM24CL64 is designed to operate in a manner very similar to other 2-wire interface memory products. The major differences result from the higher performance write capability of FRAM technology. These improvements result in some differences between the FM24CL64 and a similar configuration EEPROM during writes. The complete operation for both writes and reads is explained below.

### Write Operation

All writes begin with a device address, then a memory address. The bus master indicates a write operation by setting the LSB of the device address to a 0. After addressing, the bus master sends each byte of data to the memory and the memory generates an acknowledge condition. Any number of sequential bytes may be written. If the end of the address range is reached internally, the address counter will wrap from 1FFFh to 0000h.

Unlike other nonvolatile memory technologies, there is no effective write delay with FRAM. Since the read and write access times of the underlying memory are the same, the user experiences no delay through the bus. The entire memory cycle occurs in less time than a single bus clock. Therefore, any operation including read or write can occur immediately following a write. Acknowledge polling, a technique used with EEPROMs to determine if a write is complete is unnecessary and will always return a ready condition.

Internally, an actual memory write occurs after the 8<sup>th</sup> data bit is transferred. It will be complete before the acknowledge is sent. Therefore, if the user desires to abort a write without altering the memory contents, this should be done using start or stop condition prior to the 8<sup>th</sup> data bit. The FM24CL64 uses no page buffering.

The memory array can be write protected using the WP pin. Setting the WP pin to a high condition (VDD) will write-protect all addresses. The FM24CL64 will not acknowledge data bytes that are written to protected addresses. In addition, the address counter will not increment if writes are attempted to these addresses. Setting WP to a low state (VSS) will deactivate this feature. WP is pulled down internally.

Figure 5 below illustrates both a single-byte and multiple-write.

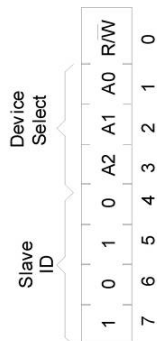


Figure 4. Slave Address

### Addressing Overview

After the FM24CL64 (as receiver) acknowledges the device address, the master can place the memory address on the bus for a write operation. The address requires two bytes. The first is the MSB. Since the device uses only 13 address bits, the value of the upper three bits are don't care. Following the MSB is the LSB with the remaining eight address bits. The address value is latched internally. Each access causes the latched address value to be incremented automatically. The current address is the value that is held in the latch -- either a newly written value or the address following the last access. The current address will be held for as long as power remains or until a new value is written. Reads always use the current address. A random read address can be loaded by beginning a write operation as explained below.

After transmission of each data byte, just prior to the acknowledge, the FM24CL64 increments the internal address latch. This allows the next sequential byte to be accessed with no additional addressing. After the last address (1FFFh) is reached, the address latch will roll over to 0000h. There is no limit to the number of bytes that can be accessed with a single read or write operation.

### Data Transfer

After the address information has been transmitted, data transfer between the bus master and the FM24CL64 can begin. For a read operation the FM24CL64 will place 8 data bits on the bus then wait for an acknowledge from the master. If the acknowledge occurs, the FM24CL64 will transfer the next sequential byte. If the acknowledge is not sent, the FM24CL64 will end the read operation. For a write operation, the FM24CL64 will accept 8 data bits from the master then send an acknowledge. All data transfer occurs MSB (most significant bit) first.

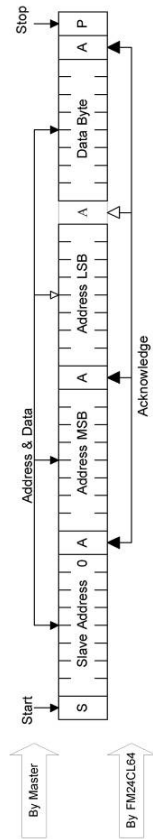


Figure 5. Single Byte Write

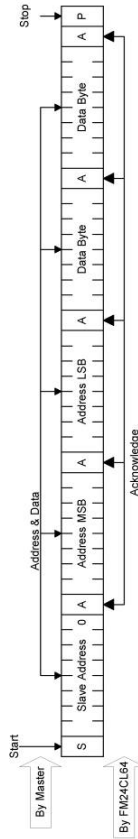


Figure 6. Multiple Byte Write

### Read Operation

There are two basic types of read operations. They are current address read and selective address read. In a current address read, the FM24CL64 uses the internal address latch to supply the address. In a selective read, the user performs a procedure to set the address to a specific value.

#### Current Address & Sequential Read

As mentioned above the FM24CL64 uses an internal latch to supply the address for a read operation. A current address read uses the existing value in the address latch as a starting place for the read operation. The system reads from the address immediately following that of the last operation.

To perform a current address read, the bus master supplies a device address with the LSB set to 1. This indicates that a read operation is requested. After receiving the complete device address, the FM24CL64 will begin shifting out data from the current address on the next clock. The current address is the value held in the internal address latch.

Beginning with the current address, the bus master can read any number of bytes. Thus, a sequential read is simply a current address read with multiple byte transfers. After each byte the internal address counter will be incremented.

*Each time the bus master acknowledges a byte, this indicates that the FM24CL64 should read out the next sequential byte.*

There are four ways to properly terminate a read operation. Failing to properly terminate the read will most likely create a bus contention as the FM24CL64 attempts to read out additional data onto the bus. The four valid methods are:

1. The bus master issues a no-acknowledge in the 9<sup>th</sup> clock cycle and a stop in the 10<sup>th</sup> clock cycle. This is illustrated in the diagrams below. This is preferred.
2. The bus master issues a no-acknowledge in the 9<sup>th</sup> clock cycle and a start in the 10<sup>th</sup>.
3. The bus master issues a stop in the 9<sup>th</sup> clock cycle.
4. The bus master issues a start in the 9<sup>th</sup> clock cycle.

If the internal address reaches 1FFFh, it will wrap around to 0000h on the next read cycle. Figures 7 and 8 below show the proper operation for current address reads.

#### Selective (Random) Read

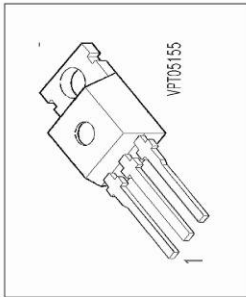
There is a simple technique that allows a user to select a random address location as the starting point for a read operation. This involves using the first three bytes of a write operation to set the internal address followed by subsequent read operations.

To perform a selective read, the bus master sends out the device address with the LSB set to 0. This specifies a write operation. According to the write protocol, the bus master then sends the address bytes



SIPMOS® Power Transistor

- N channel
- Enhancement mode
- Avalanche-rated



Pin 1	Pin 2	Pin 3
G	D	S

Type	V <sub>DS</sub>	I <sub>D</sub>	R <sub>DS(on)</sub>	Package	Ordering Code
BUZ 60	400 V	5.5 A	1 Ω	TO-220 AB	C67078-S1312-A2

Maximum Ratings

Parameter	Symbol	Values	Unit
Continuous drain current	I <sub>D</sub>	5.5	A
Pulsed drain current	I <sub>D(puls)</sub>	22	
T <sub>C</sub> = 25 °C			
Avalanche current, limited by T <sub>Jmax</sub>	I <sub>AR</sub>	5.5	
Avalanche energy, periodic limited by T <sub>Jmax</sub>	E <sub>AR</sub>	8	mJ
Avalanche energy, single pulse	E <sub>AS</sub>		
I <sub>D</sub> = 5.5 A, V <sub>DD</sub> = 50 V, R <sub>GS</sub> = 25 Ω L = 18.5 mH, T <sub>J</sub> = 25 °C		320	
Gate source voltage	V <sub>GS</sub>	±20	V
Power dissipation	P <sub>tot</sub>	75	W
T <sub>C</sub> = 25 °C			
Operating temperature	T <sub>J</sub>	-55 ... +150	°C
Storage temperature	T <sub>stg</sub>	-55 ... +150	
Thermal resistance, chip case	R <sub>thJC</sub>	≤ 1.67	K/W
Thermal resistance, chip to ambient	R <sub>thJA</sub>	75	
DIN humidity category, DIN 40 040		E	
IEC climatic category, DIN IEC 68-1		55 / 150 / 56	

Semiconductor Group

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07/96



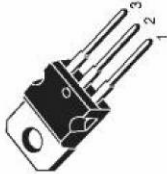
N - CHANNEL 50V - 0.03Ω - 33A TO-220  
STripFET™ MOSFET

TYPE	V <sub>DS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
BUZ11	50 V	< 0.04 Ω	33 A

- TYPICAL R<sub>DS(on)</sub> = 0.03 Ω
- AVALANCHE RUGGED TECHNOLOGY
- 100% AVALANCHE TESTED
- HIGH CURRENT CAPABILITY
- 175°C OPERATING TEMPERATURE

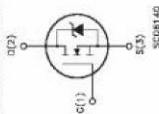
APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SOLENOID AND RELAY DRIVERS
- REGULATORS
- DC-DC & DC-AC CONVERTERS
- MOTOR CONTROL, AUDIO AMPLIFIERS
- AUTOMOTIVE ENVIRONMENT (INJECTION, ABS, AIR-BAG, LAMP DRIVERS, Etc.)



TO-220

INTERNAL SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

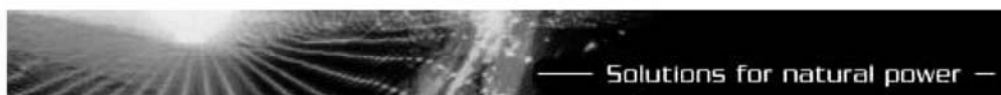
Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	50	V
V <sub>DSR</sub>	Drain- gate Voltage (R <sub>GS</sub> = 20 kΩ)	50	V
V <sub>GS</sub>	Gate-source Voltage	± 20	V
I <sub>D</sub>	Drain Current (continuous) at T <sub>C</sub> = 25 °C	33	A
I <sub>DM</sub>	Drain Current (pulsed)	134	A
P <sub>tot</sub>	Total Dissipation at T <sub>C</sub> = 25 °C	90	W
T <sub>stg</sub>	Storage Temperature	-65 to 175	°C
T <sub>J</sub>	Max. Operating Junction Temperature	175	°C

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> I <sub>D</sub> = 1 mA	2.1	3	4	V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10V I <sub>D</sub> = 19 A		0.03	0.04	Ω

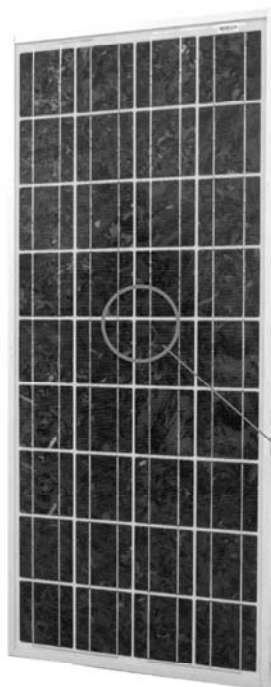
R <sub>thj-case</sub>	Thermal Resistance Junction-case	Max	1.67			°C/W
R <sub>thj-amb</sub>	Thermal Resistance Junction-ambient	Max	62.5			°C/W



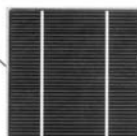
# PANNEAU SOLAIRE



## PWX500- 12 V HAUTE FIABILITE MODULE PHOTOVOLTAIQUE - JBox



- Télécommunication
- Télévision communautaire
- Protection cathodique
- Signalisation
- Hôpital, dispensaire de brousse
- Electrification rurale
- Pompage
- Couplage au réseau



Le PWX500 est fabriqué à partir de 4 X 9 cellules polycristallines 4 pouces (101,50 mm X 101,50 mm) à haut rendement.

Le PWX500 est un module bi-verre, parfaitement adapté aux conditions climatiques et environnementales sévères grâce au verre en face avant et en face arrière qui lui confère un isolement électrique et une fiabilité accrues.

Le module PWX500 utilise la technologie des cellules multicristallines PHOTOWATT. Les cellules solaires sont mesurées individuellement et triées électroniquement avant d'être interconnectées. L'encapsulation des cellules est réalisée entre deux plaques de verre trempé. L'encapsulant, de l'EVA résistant aux UV, enrobe les cellules photovoltaïques à l'intérieur des laminés protégeant ainsi les cellules de la corrosion. Le PWX500 bénéficie donc des garanties de l'excellente résistance mécanique du verre, à la fois en face avant et en face arrière.

Le cadre auto-porteur en aluminium anodisé a été étudié pour permettre une facilité de fixation tant par l'avant que par l'arrière. Ce module est disponible en version verre / tedlar PW500, plus léger tout en bénéficiant de propriétés électriques identiques.

Pour les applications intégrées au bâtiment sur structure existante, ce module peut être livré sans le cadre aluminium. Veuillez nous consulter pour tout complément d'information.

**GARANTIE PUISSANCE : 25 ANS\***

**GARANTIE PRODUIT : 5 ANS\***

PWX500		Configuration 12 V		
Puissance typique	W	45	50	55
Puissance minimale	W	40,1	45,1	50,1
Tension à la puissance typique	V	16,9	17,2	17,3
Intensité à la puissance typique	A	2,65	2,9	3,2
Intensité de court circuit	A	2,95	3,1	3,45
Tension en circuit ouvert	V	21,6	21,6	21,7
Tension maximum du circuit	V	600V DC		
Coefficients de température		$\alpha = +0,95 \text{ mV}/^{\circ}\text{C}$ ; $\beta = -79 \text{ mV}/^{\circ}\text{C}$ ; $\gamma \text{ P/P} = -0,43 \text{ \% }/^{\circ}\text{C}$		
Spécifications de puissance à 1000 W/m <sup>2</sup> : 25°C : AM 1,5				



\*Selon les conditions générales de garantie

Informations sujettes à évolutions - Dernière mise à jour : Septembre 2003

PRECISION 2.5 VOLT LOW KNEE CURRENT  
VOLTAGE REFERENCE  
ISSUE 3 - MARCH 1998

ZRC250

DEVICE DESCRIPTION

The ZRC250 uses a bandgap circuit design to achieve a precision micropower voltage reference of 2.5 volts. The device is available in small outline surface mount packages, ideal for applications where space saving is important, as well as packages for through hole requirements.

The ZRC250 design provides a stable voltage without an external capacitor and is stable with capacitive loads. The ZRC250 is recommended for operation between 20µA and 5mA and so is ideally suited to low power and battery powered applications.

Excellent performance is maintained to an absolute maximum of 25mA, however the rugged design and 20 volt processing allows the reference to withstand transient effects and currents up to 200mA. Superior switching capability allows the device to reach stable operating conditions in only a few microseconds.

FEATURES

- Small outline SOT23 and SO8 packages
- TO92 style packages
- No stabilising capacitor required
- Low knee current, 15µA typical
- Typical  $T_C$  30ppm/°C
- Typical slope resistance 0.4Ω
- ± 3, 2 and 1% tolerance
- Industrial temperature range
- Operating current 20µA to 5mA
- Transient response, stable in less than 1µs
- Optional extended current range

APPLICATIONS

- Battery powered and portable equipment.
- Instrumentation.
- Test equipment.

ZRC250

**ABSOLUTE MAXIMUM RATING**

Reverse Current	25mA
Forward Current	25mA
Operating Temperature	-40 to 85°C
Storage Temperature	-55 to 125°C

**Power Dissipation ( $T_{mi}=25^{\circ}\text{C}$ )**

SOT23	330mW
E-line, 3 pin (TO92)	500mW
E-line, 2 pin (TO92)	500mW
SO8	625mW

**ELECTRICAL CHARACTERISTICS**  
**TEST CONDITIONS (Unless otherwise stated)  $T_{mi}=25^{\circ}\text{C}$**

SYMBOL	PARAMETER	CONDITIONS	LIMITS			TOL %	UNITS
			MIN	TYP	MAX		
$V_R$	Reverse Breakdown Voltage	$I_R=15\mu\text{A}$	2.475	2.5	2.525	1	V
			2.45	2.5	2.55	2	
			2.425	2.5	2.575	3	
$I_{MIN}$	Minimum Operating Current		13	20			µA
$I_R$	Recommended Operating Current		0.02	5			mA
$T_C$ †	Average Reverse Breakdown Voltage Temp. Co.	$I_{R(min)}$ to $I_{R(max)}$	30	90			ppm/°C
$R_S$ §	Slope Resistance		0.4	1			Ω
$Z_R$	Reverse Dynamic Impedance	$I_R=1\text{mA}$ $f=100\text{Hz}$ $I_{AC}=0.1 I_R$	0.3	0.8			Ω
$E_N$	Wideband Noise Voltage	$I_R=15\mu\text{A}$ $f=10\text{Hz to }10\text{kHz}$	60				µV(rms)

$$\dagger T_C = \frac{(V_{R(max)} - V_{R(min)})}{V_R \times (T_{(max)} - T_{(min)})} \times 1000000$$

Note:  $V_{R(max)} - V_{R(min)}$  is the maximum deviation in reference voltage measured over the full operating temperature range.

$$\S R_S = \frac{V_R \text{ Change}(I_{R(min)} \text{ to } I_{R(max)})}{I_{R(max)} - I_{R(min)}}$$

